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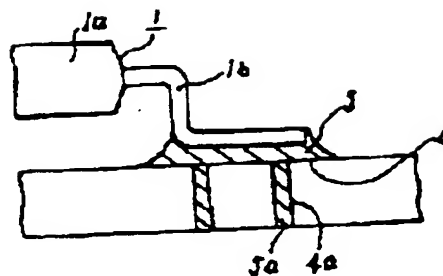
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TITLE : PRINTED SUBSTRATE



**ABSTRACT :** PURPOSE: To acquire a printed substrate wherein rupture is not caused by thermal stress, etc., between a connection land and a surface package semiconductor element lead thereof by providing at least one through-hole wherein solder enters to a part immediately below each connection land whereto a surface package semiconductor element is fixed.

CONSTITUTION: A specified amount of solder paste is applied to a part of a connection land 4 of a printed substrate by using a printer, etc. A surface package semiconductor element 1 is mounted on a specified position on the printed substrate, that is, on a connection land 2 of the printed substrate by using a part mounting device, etc., by positioning a fixing surface of a lead 1b accurately. Lastly, by performing thermal heating treatment such as reflow all over the printed substrate, solder paste is fused and enters also a through-hole 4a. Therefore, the lead 1b is surely sealed to the printed substrate with an enlarged soldered area at the side of a connection land 4 of the printed substrate and a printed substrate which is not ruptured by heat stress, etc., can be acquired.

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